



WIDEBAND POWER AMPLIFIER MODULE, 2 - 20 GHz

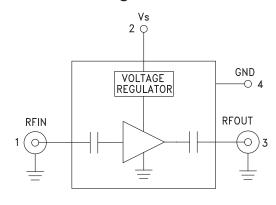


Typical Applications

The HMC-C003 Wideband PA is ideal for:

- Telecom Infrastructure
- Microwave Radio & VSAT
- Military & Space
- Test Instrumentation
- Fiber Optics

Functional Diagram



Features

P1dB Output Power: +26 dBm @ 10 GHz

Output IP3: +34 dBm

Gain: 15 dB

50 Ohm Matched Input/Output

Regulated Supply and Bias Sequencing

Hermetically Sealed Module

Field Replaceable SMA connectors

-55 to +85°C Operating Temperature

General Description

The HMC-C003 is a GaAs MMIC PHEMT Distributed Power Amplifier in a miniature, hermetic module with replaceable SMA connectors which operates between 2 and 20 GHz. The self-biased amplifier provides 15 dB of gain, +34 dBm output IP3 and up to +26 dBm of output power at 1 dB gain compression while requiring a single +12V supply. Gain flatness is excellent from 2 - 18 GHz making the HMC-C003 ideal for EW, ECM RADAR and test equipment applications. The wideband amplifier I/Os are internally matched to 50 Ohms and are internally DC blocked.

Electrical Specifications, $T_{\Delta} = +25^{\circ}$ C, Vs = +11.6V to +12.4V

Parameter	Min.	Тур.	Max.	Min.	Тур.	Max.	Min.	Тур.	Max.	Units
Frequency Range	2.0 - 6.0		6.0 - 18.0		18.0 - 20.0			GHz		
Gain	13	15		11	14		9	12		dB
Gain Flatness		±.025			±0.75			±1.0		dB
Gain Variation Over Temperature		0.02	0.03		0.02	0.03		0.02	0.03	dB/ °C
Noise Figure		4.0			4.0			6.0		dB
Input Return Loss		17			18			10		dB
Output Return Loss		12			10			12		dB
Output Power for 1 dB Compression (P1dB)	23	26		20	24		19	22		dBm
Saturated Output Power (Psat)		27			25			23		dBm
Output Third Order Intercept (IP3)		34			30			25		dBm
Spurious Response		-50			-60			-60		dBc
Supply Current		310	350		310	350		310	350	mA

HMC-C003* PRODUCT PAGE QUICK LINKS

Last Content Update: 11/29/2017

COMPARABLE PARTS -

View a parametric search of comparable parts.

DOCUMENTATION

Application Notes

 AN-1363: Meeting Biasing Requirements of Externally Biased RF/Microwave Amplifiers with Active Bias Controllers

Data Sheet

· HMC-C003 Data Sheet

TOOLS AND SIMULATIONS 🖵

· HMC-C003 S-Parameter

REFERENCE MATERIALS 🖵

Technical Articles

 Wideband Amplifier and Prescaler Modules Cover DC to 20 GHz

DESIGN RESOURCES

- HMC-C003 Material Declaration
- PCN-PDN Information
- · Quality And Reliability
- Symbols and Footprints

DISCUSSIONS •

View all HMC-C003 EngineerZone Discussions.

SAMPLE AND BUY 🖵

Visit the product page to see pricing options.

TECHNICAL SUPPORT 🖳

Submit a technical question or find your regional support number.

DOCUMENT FEEDBACK 🖳

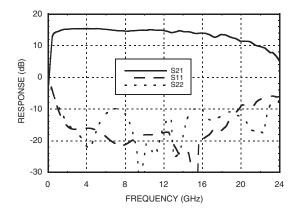
Submit feedback for this data sheet.



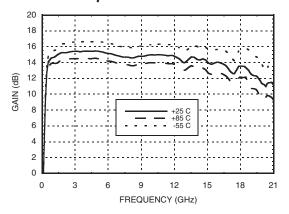


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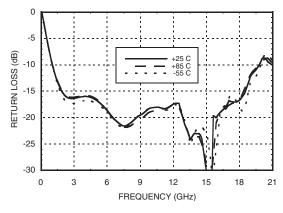
Gain & Return Loss



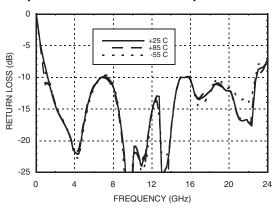
Gain vs. Temperature



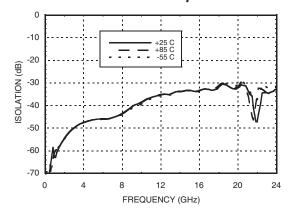
Input Return Loss vs. Temperature



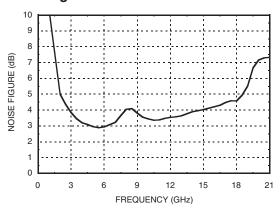
Output Return Loss vs. Temperature



Reverse Isolation vs. Temperature



Noise Figure

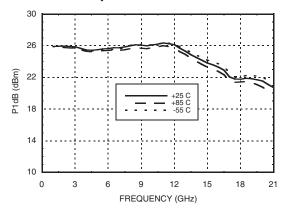




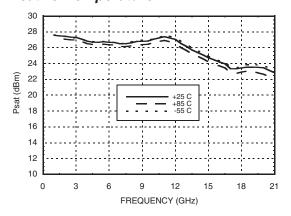


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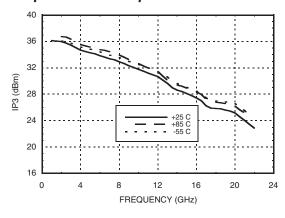
P1dB vs. Temperature



Psat vs. Temperature



Output IP3 vs. Temperature



Absolute Maximum Ratings

Bias Supply Voltage (Vs)	+11 Vdc to +13 Vdc		
RF Input Power (RFIN)	+23 dBm		
Storage Temperature	-65 to +150 °C		
Operating Temperature	-55 to +85 °C		



Pin Descriptions

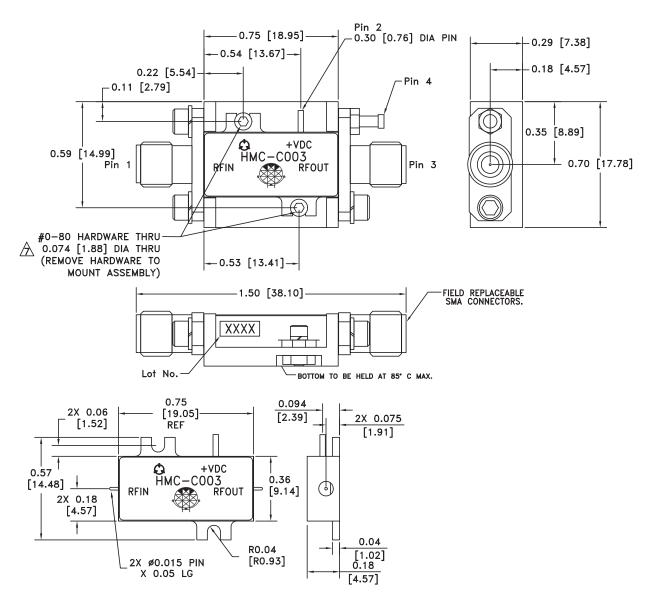
Pin Number	Function	Description	Interface Schematic		
1	RFIN & RF Ground	RF input connector, SMA female, field replaceable. This pin is AC coupled and matched to 50 Ohms.	RFINO— —		
2	Vs	Power supply voltage for the amplifier.	VS VOLTAGE REGULATOR		
3	RFOUT & RF Ground	RF output connector, SMA female. This pin is AC coupled and matched to 50 Ohms.	→ ├─○ RFOUT		
4	GND	Power supply ground.	○ GND =		





WIDEBAND POWER AMPLIFIER MODULE, 2 - 20 GHz

Outline Drawing



Package Information

· wondgo mmonmadom				
Package Type	C-2			
Package Weight [1]	11.2 gms ^[2]			
Spacer Weight	N/A			

- [1] Includes the connectors
- [2] ±1 gms Tolerance

NOTES:

- 1. PACKAGE, LEADS, COVER MATERIAL; KOVAR™
- 2. BRACKET MATERIAL: ALUMINUM
- 3. PLATING: ELECTROLYTIC GOLD 50 MICROINCHES MIN., OVER ELECTROLYTIC NICKEL 75 MICROINCHES MIN.
- 4. ALL DIMENSIONS ARE IN INCHES [MILLIMETERS].
- 5. TOLERANCES ±.005 [0.13] UNLESS OTHERWISE SPECIFIED.
- 6. FIELD REPLACEABLE SMA CONNECTORS. TENSOLITE 5602 - 5CCSF OR EQUIVALENT.
- ↑TO MOUNT MODULE TO SYSTEM PLATFORM REPLACE 0 -80 HARDWARE WITH DESIRED MOUNTING SCREWS.